

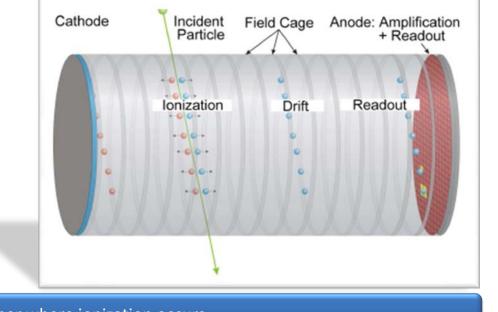


A New GEM Module for the LPTPC

By Stefano Caiazza







Gas Tight Container where ionization occurs

Well known Electric and Magnetic Fields

- To control the drifting inside the chamber
- The most simple configuration is with homogenous fields perprendicular to the readout system

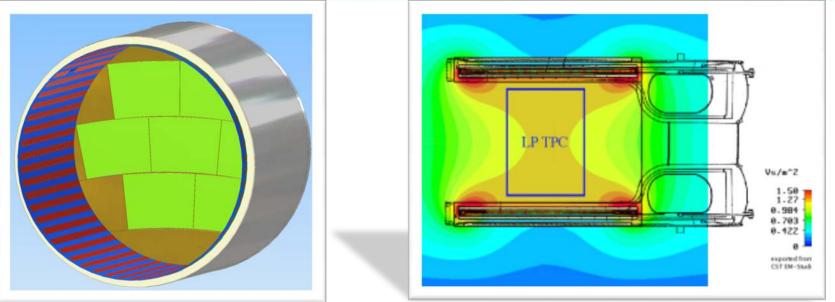
Amplification and Readout system

• Reconstruct the 3D position of the ionization clusters



Basics – Our TPC, the LPTPC





Field Cage designed by Peter Schade

- 60 cm drift length
- 72 cm inner diameter
- Designed to fit inside PCMAG

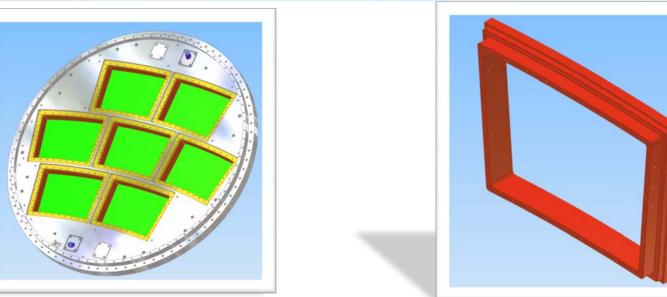
PCMAG

- Superconductive Magnet with standalone Lhe Cooling and low mass coil
- 1 Tesla Magnetic Field
- Supplied by KEK



Basics – LPTPC Endplate





Endplate

- Designed by Dan Peterson at Cornell
- Aluminum Alloy
- Accomodates seven identically shaped modules

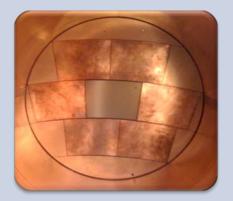
The Modules

- Cornerstone shape
- 22 cm wide (average value) Max width 24 cm
- 17 cm high

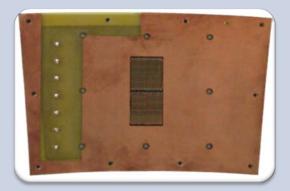


Basics – The Modules we have









Micromegas

- Built at Saclay
- Pad Readout
- Multiple versions with naked or coated pads
- Readout with T2K Electronics

Asian GEM

- Built in Japan and China
- Japanese produced GEM
- Pad Readout with Altro Electronics
- GRP Frame on the upper and lower side

Bonn GEM

- 10X10 cm Standard CERN GEM
- Pad Readout with Altro Electronis
- Pixel readout with integrated electronics

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Maximum Sensitive Area

• We will need to use a custom designed GEM

Gain Uniformity between 5/10%

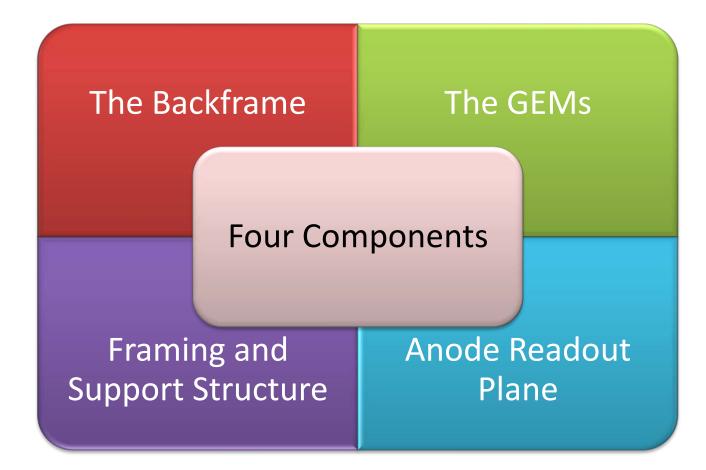
- We need to ensure a good flatness of the GEM
- The uniformity may be improved with calibration
- Good dE/dx resolution

Spatial resolution under 100 μm

• Small pad size

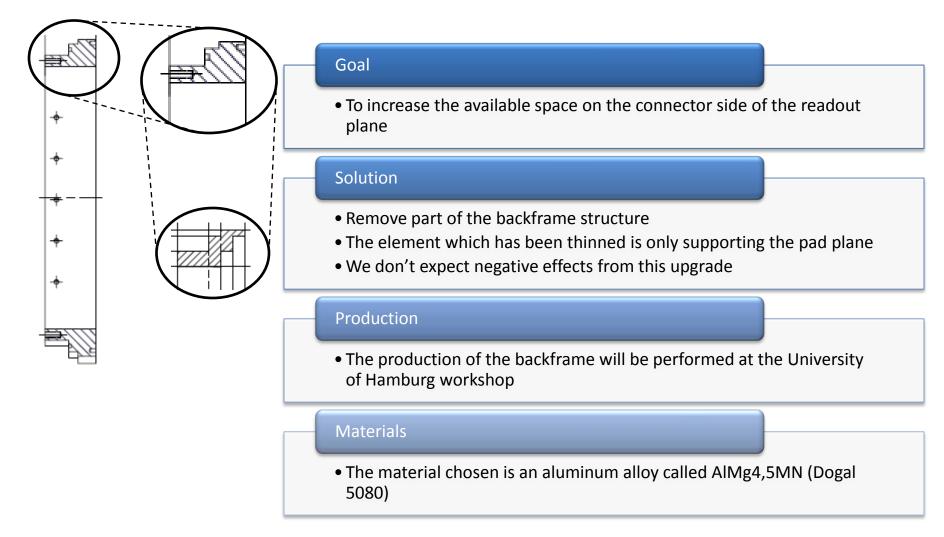






The new backframe: Design









Custom GEM

Specifically designed to get the maximum sensitive area

Produced by CERN

- 50 µm kapton foil
- Chemical etching

Standard hole size and pitch

- 70 µm hole size
- 140 μ m hole pitch

4-fold electrode segmentation

• The surface of the GEM must be segmented to reduce the damage caused by electrical discharges

Frame and Support System: Issues





Standard GEM frames made of GRP (Glass Reinforced Plastic)

- The width of the frame is about 1 cm
- No supported areas inside the frame

Decrease the size of the unsupported areas

- Gain uniformity limited by the GEM sagging
- To reduce the sagging we must limit the unsupported areas of the GEM

Increase the sensitive area

- Sensitive area limited by the presence of supporting materials
- To increase the sensitive area we need to reduce the width of the framing and supporting structure

Frame and Support System: Our Solution

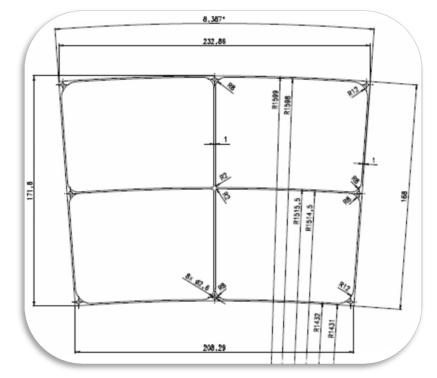


What we need:

- Insulating material stif GRP
- The material should be machinable at thicknesses smaller than 1 cm

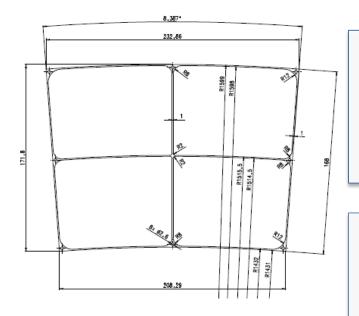
What we choose:

- Alumina Ceramics
- Almost 4 times stiffer than GRP
- May be machined with widths up to 0.3 mm



Frame and Support System: Main Features





Modular structure

- Every GEM can be separately framed
- The framed GEM can be piled up to form the stack using "ungemmed" frames as spacers
- There are 8 strong points for the mounting and aligning of the support structure

1.0 mm width

- The external frame and the internal grid structure are 1.0 mm wide
- Smaller widths were considered and discarded because of insufficient resistence

Grid patterns

- Many grid patterns have been considered
- The one shown has been selected for the first tests

Production

• We are in contact with two firms and evaluating their proposals



ED

E_{T1}

E₇₂

E

E_{Hole1}, U_{GEM1}

EHOIE2, UGEM2

E_{Hole3}, U_{GEM2}



Three GEM + possible gate

- Three GEM stack
- Optional fourth module (gating)
- The gate may be both GEM or wire based

Time resolution

- Small induction gap \rightarrow better time resolution
- Time resolution depends also on the longitudinal diffusion during drift

Defocussing

- Gap's size and fields influence the defocussing of the electron clouds
- The defocussing and the pad size influence the point resolution

Ion backdrift

• Influenced by the fields and of the potential across the GEMs

Gap size and field intensities not yet finalized

• Simulation and calculation will be performed in the near future to find the best compromise



Cathode

d_D

d_{T1}

d_{T2}

d.

Anode

۲

Ψıî

L2

GEM10

GEM1/

GEM20

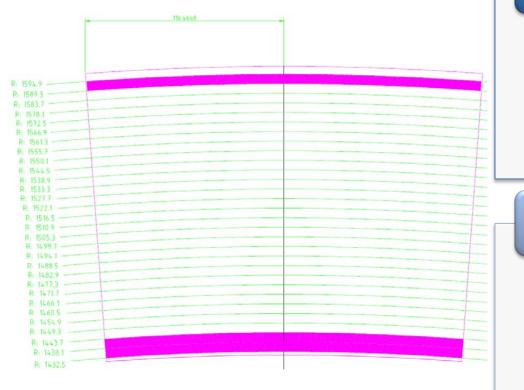
GEM2A

GEM3C

GEM3A







Structural Features

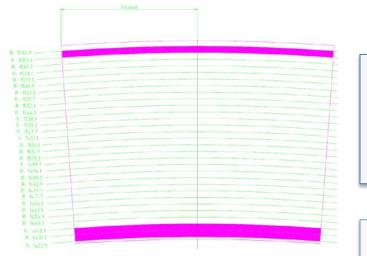
- Ensure gas tightness
- Support the GEM stack
- Provide power to the GEM stack

Readout Features

- Pad readout
- Maximum possible sensitive area
- Readout by ALTRO electronics







In collaboration with Bonn University

- The design is still in his infancy
- Using the data acquired testing the Bonn GEM module

Pad size

- (1.1 ÷ 1.25) x (5.6 ÷ 5.8) mm
- 28 rows
- Row gaps aligned with the GEM segmentation gap

GEM Power supply

- Supplied from power pads on the PCB itself
- Using the ceramic structure to separate the power from the readout pads





Gain Calibration

- Beam calibration
- Laser calibration
- Radioactive source calibration

Gate efficiency

• Confront the efficiency of GEM and wire gates

Ion Backdrift Measurement

• We need the equipment to perform this measurements on the LP





Module Backframe

- First design ready
- Production of the first prototype began

Ceramic Framing

- First design ready
- Evaluating producer's offers

GEMs

- First design ready
- Getting feedback from CERN to update this design

Anode Readout Plane

• Design just beginning

Other ideas

- Compare gating modules
- Test the gain homogeneity of the modules
- Measure the ion backdrift in the TPC